



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#9/B-823  
Hawkins  
6/10/03

In re the Application of:

Lamson, et al.

Docket No.: TI-31189

Serial No.: 09/989,263

Examiner: Maldonado, J.J.

Filed: 11/19/01

Art Unit: 2823

For: Low Capacitance Coupling Wire Bonded Semiconductor Device

Amendment under 37 CFR 1.111

Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. 201.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

5-28-03

*Michael K. Skrehot*

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 02/28/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.